

Title (en)
HOT PLATE AND CONDUCTOR PASTE

Title (de)
HEIZPLATTE UND LEITFÄHIGE PASTE

Title (fr)
PLAQUE CHAUFFANTE ET PÂTE CONDUCTRICE

Publication
EP 1185143 A4 20050307 (EN)

Application
EP 00922933 A 20000501

Priority

- JP 0002874 W 20000501
- JP 12697399 A 19990507
- JP 32306199 A 19991112
- JP 2000126786 A 20000427

Abstract (en)
[origin: EP1185143A1] A hot plate that does not expand much, has superior adhesion, and is provided with a conductive pattern layer having a large specific resistance. The hot plate 3 uses a ceramic nitride substrate 9, which includes conductive patterns 10, 10a. The conductive pattern layers 10, 10a is formed from ruthenium oxide, bismuth or its oxide, glass frit, and noble metal grains. <IMAGE>

IPC 8 full level
H05B 3/20 (2006.01); **H01B 1/22** (2006.01); **H01C 7/00** (2006.01); **H01L 21/027** (2006.01); **H05B 3/10** (2006.01); **H05B 3/12** (2006.01); **H05B 3/14** (2006.01); **H05B 3/16** (2006.01); **H05B 3/26** (2006.01); **H05B 3/74** (2006.01)

CPC (source: EP US)
H05B 3/12 (2013.01 - EP); **H05B 3/141** (2013.01 - EP); **H05B 3/143** (2013.01 - EP US); **H05B 3/265** (2013.01 - EP); **H05B 3/74** (2013.01 - EP)

Citation (search report)

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- [XY] GB 1528166 A 19781011 - SHOEI CHEM INC
- [Y] DE 19754235 A1 19990107 - FCT SYSTEME DER STRUKTURKERAMI [DE]
- [Y] PATENT ABSTRACTS OF JAPAN vol. 016, no. 324 (E - 1234) 15 July 1992 (1992-07-15)
- [X] PATENT ABSTRACTS OF JAPAN vol. 006, no. 074 (M - 127) 11 May 1982 (1982-05-11)

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DOCDB simple family (publication)
EP 1185143 A1 20020306; EP 1185143 A4 20050307; EP 1185143 A9 20020515; JP 2001203066 A 20010727; WO 0069218 A1 20001116

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